

#13

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Corisis et al.

Serial No.: 09/819,874

Filed: March 28, 2001

For: INTEGRATED CIRCUIT PACKAGE
ALIGNMENT FEATURE

Confirmation No.: 2037

Examiner: K. Quinto

Group Art Unit: 2826

Attorney Docket No.: 3770.3US
(97-0332.3)

NOTICE OF EXPRESS MAILING

Express Mail Mailing Label Number: EV092485206US

Date of Deposit with USPS: October 23, 2002

Person making Deposit: Jon Wentz

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Box 313b
Commissioner for Patents
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO/SB/08 be considered by the Examiner and made of record. The listed documents were cited by the office in co-pending application Serial No. 09/944,472, filed on August 30, 2001, and directed to a related invention. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as

RECEIVED

OCT 23 2002

OFFICE OF PETITIONS

Serial No.: 09/819,874

defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Publication Date</u>	<u>Patentee</u>
US - 3,932,934	01/20/1976	Lynch et al.
US - 4,142,286	03/06/1979	Knuth et al.
US - 4,528,747	07/16/1985	Hoffman et al.
US - 5,688,127	11/18/1997	Staab et al.
US - 4,722,135	02/02/1988	Read
US - 4,733,462	03/29/1988	Kawatani
US - 4,810,154	03/07/1989	Klemmer et al.
US - 4,940,181	07/10/1990	Juskey, Jr. et al.
US - 4,975,079	12/04/1990	Beaman et al.
US - 4,985,107	01/15/1991	Conroy et al.
US - 5,006,792	04/09/1991	Malhi et al.
US - 5,034,802	07/23/1991	Liebes, Jr. et al.
US - 5,051,339	09/24/1991	Friedrich et al.
US - 5,051,813	09/24/1991	Schneider et al.
US - 5,056,216	10/15/1991	Madou et al.
US - 5,074,036	12/24/1991	Dunaway et al.
US - 5,155,905	10/20/1992	Miller, Jr.
US - 5,164,818	11/17/1992	Blum et al.
US - 5,189,507	02/23/1993	Carlomagno et al.
US - 5,203,075	04/20/1993	Angulas et al.
US - 5,255,431	10/26/1993	Burdick
US - 5,329,423	07/12/1994	Scholz
US - 5,337,219	08/09/1994	Carr et al.
US - 5,376,010	12/27/1994	Petersen
US - 5,400,220	03/21/1995	Swamy
US - 5,403,671	04/04/1995	Holzmann
US - 5,435,482	07/25/1995	Variot et al.

Serial No.: 09/819,874

US - 5,435,732	07/25/1995	Angulas et al.
US - 5,442,852	08/22/1995	Danner
US - 5,446,960	09/05/1995	Isaacs et al.
US - 5,453,581	09/26/1995	Liebman et al.
US - 5,459,287	10/17/1995	Swamy
US - 5,463,191	10/31/1995	Bell et al.
US - 5,477,086	12/19/1995	Rostoker et al.
US - 5,477,933	12/26/1995	Nguyen
US - 5,526,974	06/18/1996	Gordon et al.
US - 5,528,461	06/18/1996	Gore et al.
US - 5,556,293	09/17/1996	Pfaff
US - 5,578,870	11/26/1996	Farnsworth et al.
US - 5,611,705	03/18/1997	Pfaff
US - 5,637,008	06/10/1997	Kozel
US - 5,637,919	06/10/1997	Grabbe
US - 5,639,323	06/17/1997	Jordan
US - 5,646,447	07/08/1997	Ramsey et al.
US - 5,669,774	09/23/1997	Grabbe
US - 5,691,041	11/25/1997	Frankeny et al.
US - 5,702,255	12/30/1997	Murphy et al.
US - 5,716,222	02/10/1998	Murphy
US - 5,726,502	03/10/1998	Beddingfield
US - 5,730,606	03/24/1998	Sinclair
US - 5,767,580	06/16/1998	Rostoker
US - 5,770,891	06/23/1998	Frankeny et al.
US - 5,796,590	08/18/1998	Klein
US - 5,947,751	09/07/1999	Massingill
US - 5,955,888	09/21/1999	Frederickson et al.
US - 5,983,477	11/16/1999	Jacks et al.

Serial No.: 09/819,874

US – 6,018,249	01/25/2000	Akram et al.
US – 6,026,566	02/22/2000	Urban et al.
US – 6,036,503	03/14/2000	Tsuchida
US – 6,037,667	03/14/2000	Hembree et al.
US – 6,040,618	03/21/2000	Akram
US – 6,042,387	03/28/2000	Jonaidi
US – 6,084,781	07/04/2000	Klein

Other Documents

PUTTLITZ et al., "C-4/CBGA Comparison with Other MLC Single Chip Package Alternatives," IEEE Transactions on Components, Packaging, and Manufacturing Technology, May 1995, pps. 250-256, Part B, Vol. 18, No.2.

GOLDMANN, Lewis S., "Statistical Model for the Inherent Tilt of Flip-Chips," Transactions of the ASME Journal of Electronic Packaging, March 1996, pps. 16-20, Vol. 118.

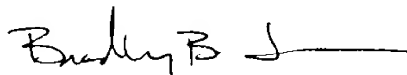
NASIATKA et al., "Determination of Optimal Solder Volume for Precision Self-Alignment of BGA using Flip-Chip Bonding," pps. 6-9.

Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

Serial No.: 09/819,874

This Supplemental Information Disclosure Statement is filed concurrent with a Request for Continued Examination (RCE) Transmittal, therefore no fee is required.

Respectfully submitted,



Bradley B. Jensen
Registration No. 46,801
Attorney for Applicants
TRASKBRITT
P.O. Box 2550
Salt Lake City, Utah 84110-2550
Telephone: 801-532-1922

Date: October 23, 2002

BBJ/hlg:djp

Enclosures: Form PTO-PTO/SB/08
Copy of documents cited

Document in ProLaw